

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	LICENSE
CONVEYING PARTY DATA	
Name	Execution Date
Chipscale, Inc.	12/14/2007

RECEIVING PARTY DATA	
Name:	Technology Properties Limited LLC
Street Address:	20400 Stevens Creek Blvd.
Internal Address:	Fifth Floor
City:	Cupertino
State/Country:	CALIFORNIA
Postal Code:	95014

PROPERTY NUMBERS Total: 20

Property Type	Number
Patent Number:	5403729
Patent Number:	5280194
Patent Number:	5656547
Patent Number:	5521420
Patent Number:	5592022
Patent Number:	5455187
Patent Number:	5441898
Patent Number:	5444009
Patent Number:	5557149
Patent Number:	5789817
Patent Number:	5910687
Patent Number:	5904496
Patent Number:	6414585
Patent Number:	6051489

OP \$800.00 5403729

Patent Number:	6121119
Patent Number:	6221751
Patent Number:	6355981
Patent Number:	6954130
Patent Number:	6833986
Patent Number:	6946734

CORRESPONDENCE DATA

Fax Number: (408)446-0905
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: (408) 886-5422
Email: mark.salvatore@tplgroup.net
Correspondent Name: Mark Salvatore
Address Line 1: 20400 Stevens Creek Blvd.
Address Line 2: Fifth Floor
Address Line 4: Cupertino, CALIFORNIA 95014

ATTORNEY DOCKET NUMBER:	TPL-0002
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NAME OF SUBMITTER:	Mark Salvatore
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Total Attachments: 7
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LICENSE

This License ("License") is entered into as of December 14, 2007 by and between ChipScale Inc. hereinafter sometimes "CSI" on the one hand, and Technology Properties Limited hereinafter sometimes "TPL" on the other hand.

NOW THEREFORE, for and in consideration of the mutual covenants herein contained as well as of other good and valuable consideration the receipt and sufficiency of which is hereby acknowledged, it is covenanted and agreed by and between the parties hereto that:

1. Subject Matter.

1.1. The patents and related materials described at Attachment I, as well as all inventions, improvements, developments, and discoveries conceived, discovered, or reduced to practice by CSI, its affiliates, licensees, and/or their respective successors-in-interest which relate to Wafer-Level Chip Scale technology, all of which is hereinafter collectively referred to as the "Chip Scale Technology".

1.2. Chip Scale Technology shall also include all rights with respect to patent rights, copyrights, mask work rights, tradenames, trademarks, trade secrets, and know-how of whatsoever kind or nature and in whatever form which relate to the Chip Scale Technology and in which CSI or its affiliates, licensees, and/or their respective successors-in-interest have an interest to the extent of such interest.

1.3. Chip Scale Technology shall also include all progeny, progenitors and enhancements of any element of the Chip Scale Technology, including specifically all additions, changes, modifications, actions, counterparts, continuations, continuations-in-part, extensions, reissues, divisionals, and/or renewals of such progenitors or progeny.

2. Grant of License.

2.1. CSI hereby grants unto TPL an exclusive, worldwide, and perpetual license with respect to those rights which enable and/or facilitate the management, development, and commercialization of the Chip Scale Technology.

2.2. In conjunction with section 2.1 above, CSI hereby grants, sets-over, assigns, transfers, and conveys unto TPL the exclusive, worldwide right to:

2.2.1. Regulate and control by license, sublicense, affiliation, or other arrangement the practice and/or use of the Chip Scale Technology;

2.2.2. Sue on and collect for its own use and benefit all claims and/or entitlements with respect to damages by reason of past infringement or use of the Chip Scale Technology; and,

2.2.3. Pursue in its own name and for its own use and benefit all remedies of whatsoever kind or nature relating to the past, present, or future infringement or use of the Chip Scale Technology.

2.3. Subject, however, to the product-related rights of IntellaSys BEC Ltd.

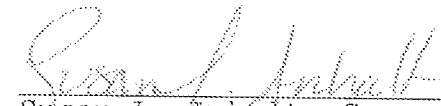
3. Attachments.

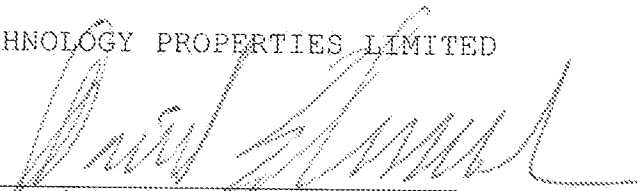
3.1. Attachment I: Schedule of CSI Patents.

IN WITNESS WHEREOF, the parties have hereunto set their hands and seals on the date first set forth above.

CHIPSCALE, INC.

TECHNOLOGY PROPERTIES LIMITED

by 
Susan L. Anhalt, Secretary

by 
Daniel E. Leckrone, Chmn

ATTACHMENT I
 SCHEDULE OF CSI PATENTS

JUR	PAT NO	DESCRIPTION	PRIORITY	FILED	ISSUED	EXPIRES
US	5,280,194	Electrical apparatus with a metallic layer coupled to a lower region of a substrate and metallic layer coupled to a lower region of a semiconductor device	9/04/1992	9/04/1992	1/18/1994	1/18/2011
US	5,403,729	Fabricating a semiconductor with an insulative coating		5/27/1992	4/4/1995	4/4/2012
US	5,441,698	Fabricating a semiconductor with an insulative coating		12/23/1994	8/15/1995	8/15/2012
US	5,444,009	Fabricating a semiconductor with an insulative coating		12/23/1994	8/22/1995	8/22/2012
US	5,521,420	Fabricating a semiconductor with an insulative coating		7/5/1994	5/28/1996	5/28/2013
US	5,592,022	Fabricating a semiconductor with an insulative coating		7/5/1994	1/7/1997	1/7/2014
US	5,455,187	Method of making a semiconductor device with a metallic layer coupled to a lower region of a substrate and metallic layer coupled to a lower region of a semiconductor device		11/1/1994	10/3/1995	10/3/2012
US	5,557,149	Semiconductor fabrication with contact processing for wrap-around flange interface		3/24/1995	9/17/1996	9/17/2013
US	5,656,547	Method for making a leadless surface mounted device with wrap-around flange interface contacts		5/11/1994	8/10/1997	8/12/2014
US	5,789,817	Electrical apparatus with a metallic layer coupled to a lower region of a substrate and a metallic layer coupled to a lower region of a semiconductor device		11/15/1996	8/4/1998	8/4/2018

COP	PAT NO	DESCRIPTION	PRIORITY	FILED	ISSUED	EXPIRES
US	5,904,496	Wafer fabrication of inside-wrapped contacts for electronic devices		1/24/1997	5/18/1999	5/18/2019
US	5,910,687	Wafer fabrication of die-bottom contacts for electronic devices		1/24/1997	6/8/1999	6/8/2019
US	6,051,489	Electronic component package with posts on the active side of the substrate		5/13/1997	4/18/2000	4/18/2020
US	6,121,119	Resistor fabrication		5/29/1997	9/19/2000	9/19/2020
US	6,221,751	Wafer fabrication of die-bottom contacts for electronic devices		6/26/1998	4/24/2001	4/24/2021
US	6,355,981	Wafer fabrication of inside-wrapped contacts for electronic devices		1/21/1999	3/12/2002	3/12/2022
US	6,414,585	Integrated passive components and package with posts		5/13/1997	7/2//2002	7/2/2022
US	6,954,130	Integrated passive components and package with posts		2/7/2002	10/11/2005	10/11/2025
US	6,833,986	Integrated passive components and package with posts		2/20/2004	12/21/2004	12/21/2024
US	6,946,734	Integrated passive components and package with posts		2/20/2004	9/20/2005	9/20/2025
HK	HK1012776	Semiconductor fabrication with contact processing for wrap-around flange interface		4/27/1995	6/23/2000	6/23/2017
HK	HK1011454	Resistor fabrication		11/30/1998	6/23/2000	6/23/2020
Singapore	34858 (W095/31829)	Semiconductor fabrication with contact processing for wrap-around flange interface		4/27/1995	3/20/1998	3/20/2015
Singapore	34853	Resistor fabrication		6/1/1995	11/16/1998	11/16/2015
UK	GB2302210	Semiconductor fabrication with contact processing for wrap-around flange interface		4/27/1995	9/16/1998	9/16/2015



JUR	PAT NO	DESCRIPTION	PRIORITY	FILED	ISSUED	EXPIRES
	GB2302452	Resistor fabrication		6/1/1995	11/18/1998	11/18/2015
UK	GB2316541	Resistor fabrication		11/7/1997	11/18/1998	11/18/2015
UK	GB2337636	Wafer fabrication of inside-wrapped contacts for electronic devices		1/26/1998	1/16/2002	1/16/2022
UK	GB2336034	Wafer fabrication of die-bottom contacts for electronic devices		1/26/1998	12/19/2001	12/19/2021
UK	GB2341003	Integrated passive components and package with posts		5/13/1998	4/3/2002	4/3/2022
UK	GB2341277	Electronic component package with posts on the active side of the substrate		5/13/1998	3/21/2002	8/21/2022
South Korea	133730	An Improved Beam Leads for Schottky-barrier diodes		11/20/1989	12/24/1997	12/24/2014
South Korea	343030	Semiconductor fabrication with contact processing for wrap-around flange interface		4/27/1995	6/21/2002	6/21/2019
South Korea	358446	Resistor fabrication		6/1/1995	10/14/2002	10/14/2019
South Korea	10-0555241	Electronic component package with posts on the active side of the substrate		5/13/1998	2/20/2006	2/20/2026
South Korea	10-0555237	Integrated passive components and package with posts		5/13/1998	2/20/2006	2/20/2026

This Schedule of Patents shall be deemed to include the items listed above, as well as all progenitors, progeny and enhancements thereof, and all additions, changes, amendments, modifications, actions, counterparts, continuations, continuations-in-part, extensions, reissues, divisionals and/or renewals of such progenitors, progeny and enhancements.

State of California
Secretary of State



I, DEBRA BOWEN, Secretary of State of the State of California, hereby certify:

That the attached transcript of 1 page(s) has been compared with the record on file in this office, of which it purports to be a copy, and that it is full, true and correct.



IN WITNESS WHEREOF, I execute this certificate and affix the Great Seal of the State of California this day of

JAN - 3 2009

DEBRA BOWEN
Secretary of State



State of California Secretary of State

LLC-1A

File #

ENDORSED - FILED In the office of the Secretary of State of the State of California

DEC 31 2008

LIMITED LIABILITY COMPANY ARTICLES OF ORGANIZATION - CONVERSION

IMPORTANT - Read all instructions before completing this form.

This Space For Filing Use Only

CONVERTED ENTITY INFORMATION

1. NAME OF LIMITED LIABILITY COMPANY (End the name with the words "Limited Liability Company," or the abbreviations "LLC" or "L.L.C." The wo "Limited" and "Company" may be abbreviated to "Ltd." and "Co.," respectively.)

TECHNOLOGY PROPERTIES LIMITED LLC

2. THE PURPOSE OF THE LIMITED LIABILITY COMPANY IS TO ENGAGE IN ANY LAWFUL ACT OR ACTIVITY FOR WHICH A LIMITED LIABILITY COMPANY MAY BE ORGANIZED UNDER THE BEVERLY-KILLEA LIMITED LIABILITY COMPANY ACT.

3. THE LIMITED LIABILITY COMPANY WILL BE MANAGED BY (Check only one)

[X] ONE MANAGER

[] MORE THAN ONE MANAGER

[] ALL LIMITED LIABILITY COMPANY MEMBER

4. MAILING ADDRESS OF THE CHIEF EXECUTIVE OFFICE

20400 Stevens Creek Blvd., Fifth Floor

CITY

Cupertino

STATE

CA

ZIP CODE

95014

5. NAME OF AGENT FOR SERVICE OF PROCESS (Item 5: Enter the name of the agent for service of process. The agent may be an individual resi in California or a corporation that has filed a certificate pursuant to California Corporations Code section 1505. Item 6: If the agent is an individual, e the agent's business or residential address in California. Item 7: If the converting entity is a California limited partnership, enter the mailing addres the individual or corporate agent. Check the box and omit the mailing address if the agent's mailing address is the same as the address in item 6.)

CT Corporation System

6. IF AN INDIVIDUAL, ADDRESS OF AGENT FOR SERVICE OF PROCESS IN CA

CITY

STATE

CA

ZIP CODE

7. MAILING ADDRESS OF AGENT FOR SERVICE OF PROCESS

CITY

STATE

ZIP CODE

[] THE MAILING ADDRESS OF THE AGENT FOR SERVICE OF PROCESS IS THE SAME AS THE AGENT'S BUSINESS OR RESIDENTIAL ADDRESS IN ITEM 6

CONVERTING ENTITY INFORMATION

8. NAME OF CONVERTING ENTITY

TECHNOLOGY PROPERTIES LIMITED

9. FORM OF ENTITY

corporation

10. JURISDICTION

California

11. CA SECRETARY OF STATE FILE NUMBER, IF ANY

C1516243

12. THE PRINCIPAL TERMS OF THE PLAN OF CONVERSION WERE APPROVED BY A VOTE OF THE NUMBER OF INTERESTS OR SHARES OF EACH C THAT EQUALED OR EXCEEDED THE VOTE REQUIRED. IF A VOTE WAS REQUIRED, PROVIDE THE FOLLOWING FOR EACH CLASS:

STATE THE CLASS AND NUMBER OF OUTSTANDING INTERESTS ENTITLED TO VOTE AND THE PERCENTAGE VOTE REQUIRED OF EACH CLA

1,000 shares of common stock

100%

ADDITIONAL INFORMATION

13. ADDITIONAL INFORMATION SET FORTH ON THE ATTACHED PAGES, IF ANY, IS INCORPORATED HEREIN BY THIS REFERENCE AND MA PART OF THIS CERTIFICATE.

14. I CERTIFY UNDER PENALTY OF PERJURY UNDER THE LAWS OF THE STATE OF CALIFORNIA THAT THE FOREGOING IS TRUE AND CORI OF MY OWN KNOWLEDGE. I DECLARE I AM THE PERSON WHO EXECUTED THIS INSTRUMENT, WHICH EXECUTION IS MY ACT AND.DEE

December 29, 2008

DATE

SIGNATURE OF AUTHORIZED PERSON

SIGNATURE OF AUTHORIZED PERSON



Daniel E. Leckrone, Chairman, CFO & Secretary TYPE OR PRINT NAME AND TITLE OF AUTHORIZED PERSON

TYPE OR PRINT NAME AND TITLE OF AUTHORIZED PERSON